

March 2015

## **FDMC86570L**

## N-Channel Shielded Gate PowerTrench® MOSFET 60 V, 84 A, 4.3 m $\Omega$

#### **Features**

- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)}$  = 4.3 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 18 A
- Max  $r_{DS(on)}$  = 6.5 m $\Omega$  at  $V_{GS}$  = 4.5 V,  $I_D$  = 15 A
- lacktriangle High performance technology for extremely low  $r_{DS(on)}$
- Termination is Lead-free
- RoHS Compliant

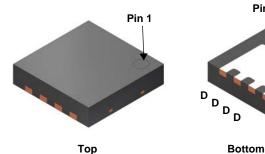


#### **General Description**

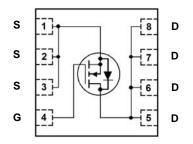
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

#### **Application**

■ DC-DC Conversion







### **MOSFET Maximum Ratings** T<sub>A</sub> = 25 °C unless otherwise noted.

Symbol		Parame	ter		Ratings	Units
V <sub>DS</sub>	Drain to Source \	/oltage			60	V
V <sub>GS</sub>	Gate to Source V	oltage			±20	V
I <sub>D</sub>	Drain Current	-Continuous	T <sub>C</sub> = 25 °C	(Note 5)	84	
		-Continuous	T <sub>C</sub> = 100 °C	(Note 5)	53	^
		-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	18	Α
		-Pulsed		(Note 4)	416	
E <sub>AS</sub>	Single Pulse Ava	lanche Energy		(Note 3)	253	mJ
D	Power Dissipatio	n	T <sub>C</sub> = 25 °C		54	W
$P_{D}$	Power Dissipation	n	T <sub>A</sub> = 25 °C	(Note 1a)	2.3	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and St	orage Junction Temperat	ure Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	2.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	53	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC86570L	FDMC86570L	Power33	13 "	12 mm	3000 units

## **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		30		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V			1	μΑ
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### **On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$ , referenced to 25 °C		-7		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 18 \text{ A}$		3.1	4.3	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		4.7	6.5	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 18 \text{ A}, T_J = 125 \text{ °C}$		5.0	6.9	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DD</sub> = 5 V, I <sub>D</sub> = 18 A		75		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 20 V V 0 V		4790	6705	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$		821	1150	рF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12		19	30	pF
R <sub>g</sub>	Gate Resistance		0.1	0.9	2.7	Ω

#### **Switching Characteristics**

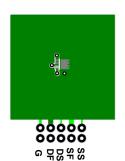
t <sub>d(on)</sub>	Turn-On Delay Time		19	34	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 18 A,	6.2	12	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	38	61	ns
t <sub>f</sub>	Fall Time		3.9	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	63	88	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 30 \text{ V},$	29	41	nC
$Q_{gs}$	Gate to Source Charge	I <sub>D</sub> = 18 A	14		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		6.3		nC

#### **Drain-Source Diode Characteristics**

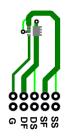
V <sub>SD</sub> Source to Drain Diode Forward Voltage	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 18 \text{ A}$ (Note 2)		0.8	1.3	V
	$V_{GS} = 0 \text{ V}, I_S = 1.9 \text{ A}$ (Note 2)		0.7	1.2	V	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 18 A, di/dt = 100 A/μs		43	69	ns
Q <sub>rr</sub>	Reverse Recovery Charge	1F = 10 A, αι/αι = 100 A/μs		26	42	nC

Notes:

<sup>1.</sup>  $R_{\theta JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta CA}$  is determined by the user's board design.



 a. 53 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b. 125 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%.
- 3.  $E_{AS}$  of 253 mJ is based on starting  $T_{J}$  = 25 °C, L = 3 mH,  $I_{AS}$  = 13 A,  $V_{DD}$  = 60 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH,  $I_{AS}$  = 43 A.
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

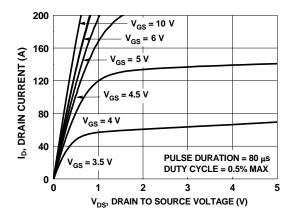


Figure 1. On-Region Characteristics

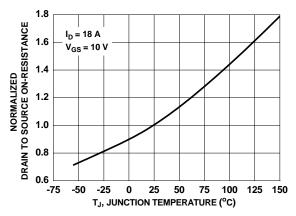


Figure 3. Normalized On-Resistance vs. Junction Temperature

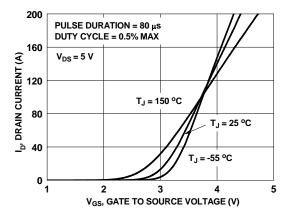


Figure 5. Transfer Characteristics

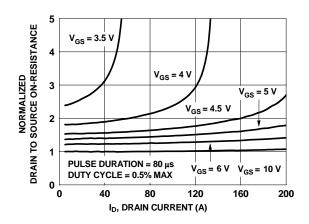


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

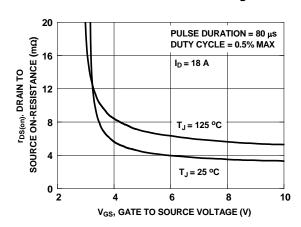


Figure 4. On-Resistance vs. Gate to Source Voltage

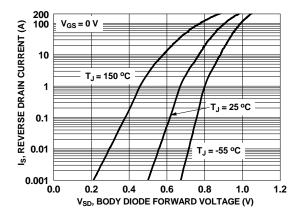


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

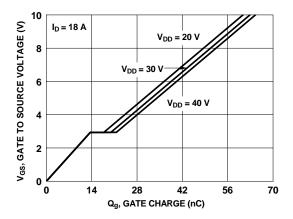


Figure 7. Gate Charge Characteristics

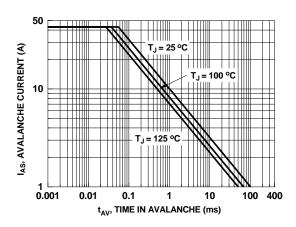


Figure 9. Unclamped Inductive Switching Capability

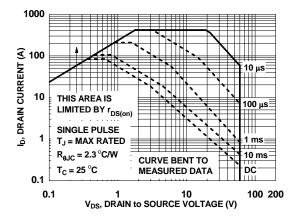


Figure 11. Forward Bias Safe Operating Area

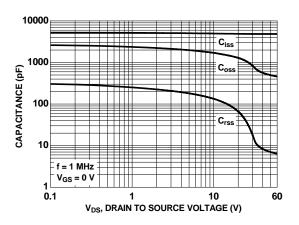


Figure 8. Capacitance vs. Drain to Source Voltage

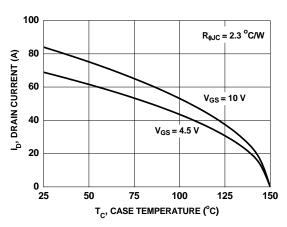


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

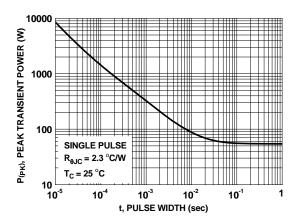


Figure 12. Single Pulse Maximum Power Dissipation

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

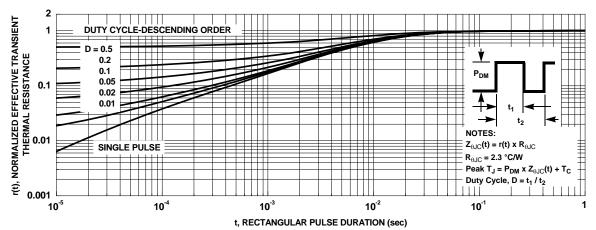
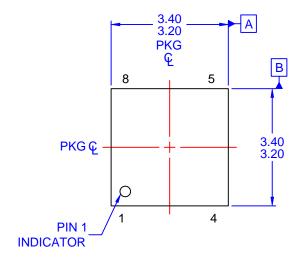
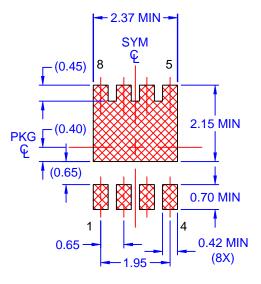
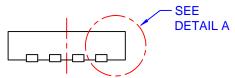


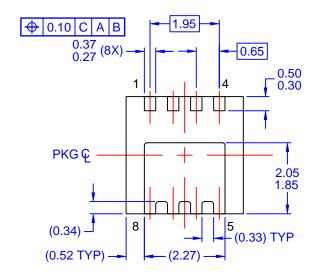
Figure 13. Junction-to-Case Transient Thermal Response Curve





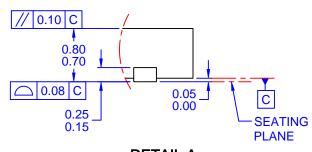


LAND PATTERN RECOMMENDATION



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- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08HREV1



DETAIL A





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Rev. 174

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